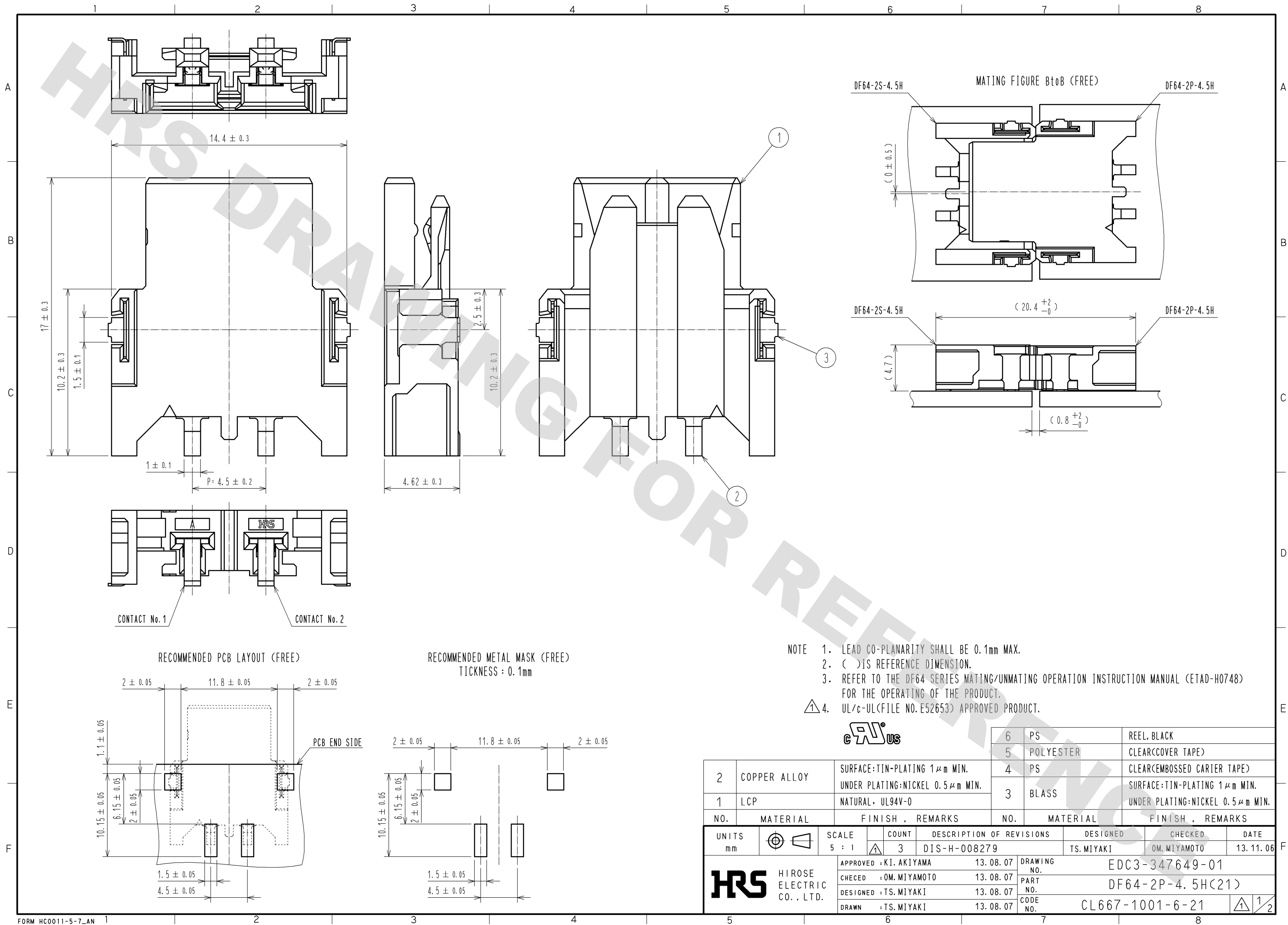
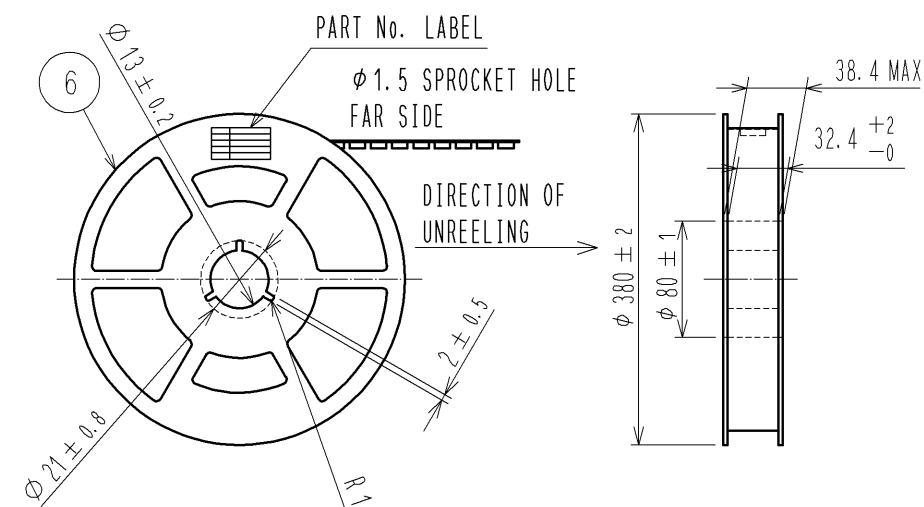
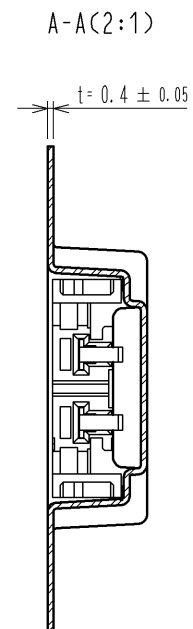
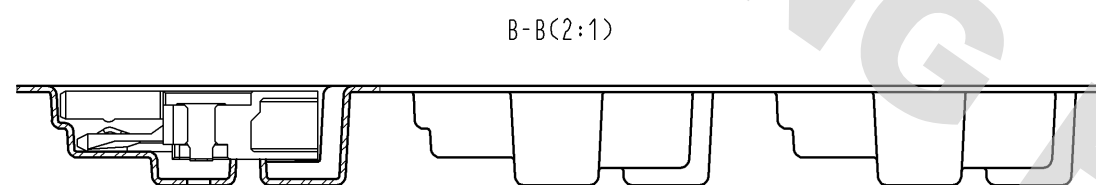






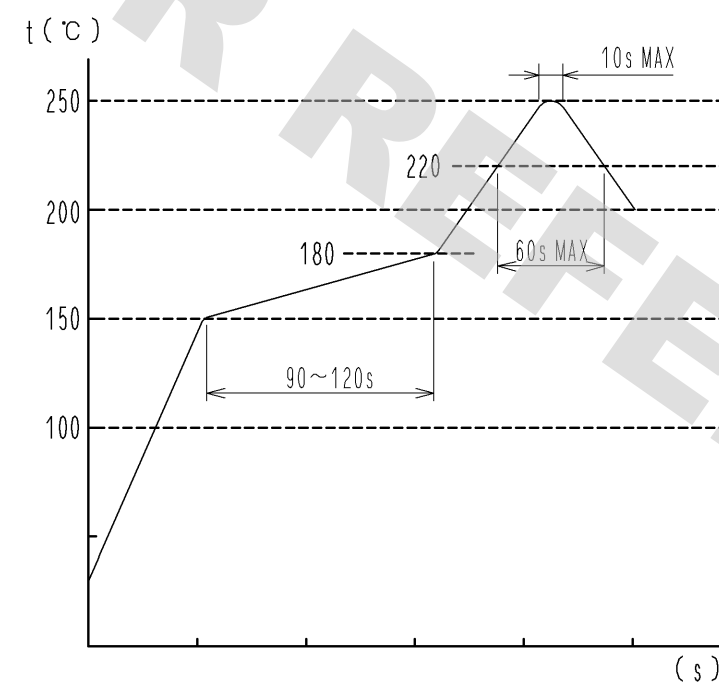
DETAIL OF PART No. LABEL

生産月日	年 月 日
図 番	CL667-1001-6-21
品 名	DF64-2P-4.5H(21)
納入数量	500 K0
納入者	ヒロセ電機(株)



DIRECTION OF REELING 

REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)



NUMBER OF REFLOW CYCLES 2 CYCLES MAX
THE TEMPERATURE IS MEASURED IN THE TERMINAL LEAD PART.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE,
PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT
THE PROFILE.
THEREFOR, A THOROUGH EVALUATION OF MOUNTING CONDITION
REQUIRED PRIOR TO PRODUCTION.
TEMPERATURE IS MEASURED AT CONTACT LEAD.

△ NOTE 5. 1 REEL:500 CONNECTORS.
 6 REEL TO JIS C 0806.(PACKAGING OF COMPONENTS FOR AUTOMATING HANDLING)
 7. () IS REFERENCE DIMENSION.